



AOS Semiconductor Product Reliability Report

AO6415, rev C

Plastic Encapsulated Device

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This AOS product reliability report summarizes the qualification result for AO6415. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AO6415 passes AOS quality and reliability requirements. The released product will be categorized by the process family and be monitored on a quarterly basis for continuously improving the product quality.

Table of Contents:

- I. Product Description
- II. Package and Die information
- III. Reliability Stress Test Summary and Result
- IV. Reliability Evaluation

I. Product Description:

The AO6415 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

- RoHS Compliant
- Halogen Free

Detailed information refers to datasheet.

II. Die / Package Information:

	AO6415
Process	Standard sub-micron Low voltage P channel
Package Type	TSOP6
Lead Frame	Cu
Die Attach	Ag epoxy
Bonding Wire	Cu wire
Mold Material	Epoxy resin with silica filler
MSL (moisture sensitive level)	Level 1 based on J-STD-020

III. Result of Reliability Stress for AO6415

Test Item	Test Condition	Time Point	Lot Attribution	Total Sample size	Number of Failures	Standard
MSL Precondition	168hr 85°C /85%RH +3 cycle reflow @260°C	-	12 lots	2618pcs	0	JESD22-A113
HTGB	Temp = 150 °c, Vgs=100% of Vgsmax	168hrs 500 hrs 1000 hrs	3 lots 4 lots 3 lots (Note A*)	770pcs 77pcs / lot	0	JESD22-A108
HTRB	Temp = 150 °c, Vds=80% of Vdsmax	168hrs 500 hrs 1000 hrs	3 lots 4 lots 3 lots (Note A*)	770pcs 77pcs / lot	0	JESD22-A108
HAST	130 +/- 2°C, 85%RH, 33.3 psi, Vgs = 100% of Vgsmax	96 hrs	11 lots (Note A*)	847pcs 77pcs / lot	0	JESD22-A110
Pressure Pot	121°C, 29.7psi, RH=100%	96 hrs	11 lots (Note A*)	847pcs 77pcs / lot	0	JESD22-A102
Temperature Cycle	-65°C to 150°C, air to air	250 / 500 cycles	12 lots (Note A*)	924pcs 77pcs / lot	0	JESD22-A104

Note A: The reliability data presents total of available generic data up to the published date.

IV. Reliability Evaluation

FIT rate (per billion): 4.16

MTTF = 27446 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size of the selected product (AO6415). Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

$$\text{Failure Rate} = \text{Chi}^2 \times 10^9 / [2 (N) (H) (Af)]$$

$$= 1.83 \times 10^9 / [2 \times (6 \times 77 \times 168 + 8 \times 77 \times 500 + 6 \times 77 \times 1000) \times 259] = 4.16$$

$$\text{MTTF} = 10^9 / \text{FIT} = 2.40 \times 10^8 \text{hrs} = 27446 \text{ years}$$

Chi² = Chi Squared Distribution, determined by the number of failures and confidence interval

N = Total Number of units from HTRB and HTGB tests

H = Duration of HTRB/HTGB testing

Af = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

Acceleration Factor [Af] = **Exp** [Ea / k (1/Tj u - 1/Tj s)]

Acceleration Factor ratio list:

	55 deg C	70 deg C	85 deg C	100 deg C	115 deg C	130 deg C	150 deg C
Af	259	87	32	13	5.64	2.59	1

Tj s = Stressed junction temperature in degree (Kelvin), K = C+273.16

Tj u = The use junction temperature in degree (Kelvin), K = C+273.16

K = Boltzmann's constant, 8.617164 X 10⁻⁵eV / K